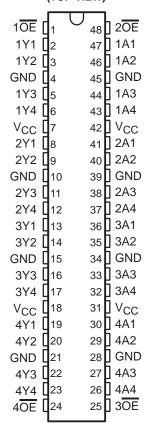
- Members of the Texas Instruments Widebus™ Family
- Inputs Are TTL-Voltage Compatible
- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- Flow-Through Architecture Optimizes
 PCB Layout
- Distributed V_{CC} and GND Pin Configurations Minimize High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1-μm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages, and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings

description

The SN54ACT16244 and 74ACT16244 are 16-bit buffers/line drivers designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. They can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. The devices provide true outputs and symmetrical \overline{OE} (active-low) output-enable inputs.

SN54ACT16244 . . . WD PACKAGE 74ACT16244 . . . DGG OR DL PACKAGE (TOP VIEW)



The 74ACT16244 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The SN54ACT16244 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74ACT16244 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE (each driver)

INP	JTS	OUTPUT
OE	Α	Υ
L	Н	Н
L	L	L
Н	Χ	Z

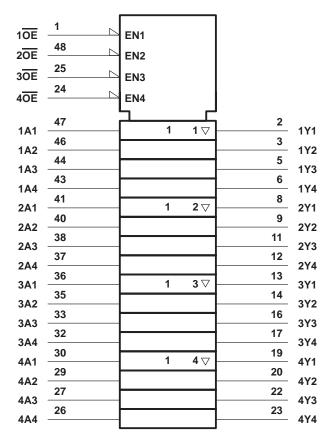


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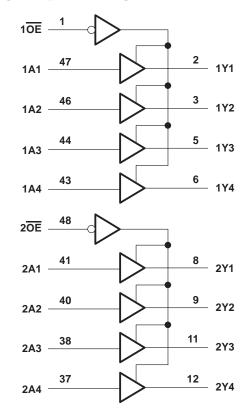
logic symbol[†]

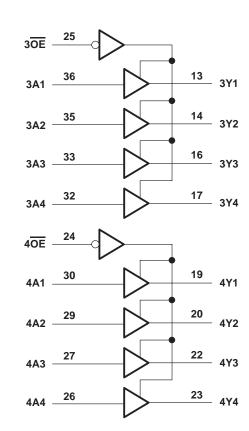


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} Input voltage range, V_{I} (see Note 1) Output voltage range, V_{O} (see Note 1) Input clamp current, I_{IK} (V_{I} < 0 or V_{I} > V_{CC}) Output clamp current, I_{OK} (V_{O} < 0 or V_{O} > V_{CC}) Continuous output current, I_{O} (V_{O} = 0 to V_{CC}) Continuous current through V_{CC} or GND	$ \begin{array}{llllllllllllllllllllllllllllllllllll$
Maximum power dissipation at $T_A = 55^{\circ}$ C (in still air) (see Note 2): DGG package	
DL package	1.2 W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.



SN54ACT16244, 74ACT16244 **16-BIT BUFFERS/LINE DRIVERS WITH 3-STATE OUTPUTS**

SCAS116B - MARCH 1990 - REVISED APRIL 1996

recommended operating conditions (see Note 3)

		SN54AC	Г16244	74ACT	16244	UNIT
		MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage (see Note 4)	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		V
V _{IL}	Low-level input voltage		0.8		0.8	V
٧ı	Input voltage	0	VCC	0	VCC	V
VO	Output voltage	0	VCC	0	VCC	V
IOH	High-level output current		-24		-24	mA
loL	Low-level output current		24		24	mA
Δt/Δν	Input transition rise or fall rate	0	10	0	10	ns/V
TA	Operating free-air temperature	-55	125	-40	85	°C

NOTES: 3. Unused inputs should be tied to V_{CC} through a pullup resistor of approximately 5 k Ω or greater to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST COMPLETIONS	V	T,	λ = 25°C	;	SN54AC	Г16244	74ACT	16244	LINIT
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	Jan 50 11 A	4.5 V	4.4			4.4		4.4		
	I _{OH} = -50 μA	5.5 V	5.4			5.4		5.4		
Vou	I _{OH} = -24 mA	4.5 V	3.94			3.7		3.8		V
VOH	10H = -24 IIIA	5.5 V	4.94			4.7		4.8		V
	$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V				3.85				
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V						3.85		
	I _{OL} = 50 μA	4.5 V			0.1		0.1		0.1	
	ΙΟΣ = 50 μΑ	5.5 V			0.1		0.1		0.1	
\/a-	10. – 24 mA	4.5 V			0.36		0.5		0.44	V
VOL	I _{OL} = 24 mA	5.5 V			0.36		0.5		0.44	V
	I _{OL} = 50 mA [†]	5.5 V					1.65			
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V							1.65	
lį	V _I = V _{CC} or GND	5.5 V			±0.1		±1		±1	μΑ
loz	$V_O = V_{CC}$ or GND	5.5 V			±0.5		±10		±5	μΑ
lcc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		160		80	μΑ
∆ICC [‡]	One input at 3.4 V, Other inputs at GND or V _{CC}	5.5 V			0.9		1		1	mA
Ci	V _I = V _{CC} or GND	5 V		4.5						pF
Co	V _O = V _{CC} or GND	5 V		13.5						pF

T Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.



^{4.} All V_{CC} and GND pins must be connected to the proper voltage supply.

[‡] This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or VCC.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T,	Վ = 25 °C		MIN	MAX	UNIT
	(5.7)	(0011 01)	MIN	TYP	MAX	IVIIIV		
^t PLH	Α	V	4	6.5	8.5	3	10.3	ns
^t PHL	1 A	,	3.4	6.3	8.7	3.4	10.1	115
^t PZH	ŌĒ	V	3	5.8	8.1	3	10.5	no
t _{PZL}	OE	ī	3.7	6.7	9.3	3.7	11	ns
^t PHZ	ŌĒ	V	5.4	8.1	11.5	5.4	13	ne
tPLZ	OE	'	5	7.5	9.5	5	10.9	ns

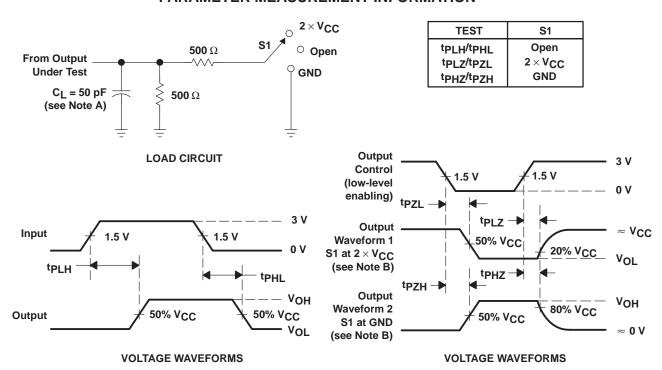
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T,	4 = 25°C	;	MIN	MAX	UNIT
	(5.7)	(0011 01)	MIN	TYP	MAX	IVIIIVI	WAX	
t _{PLH}	Λ	V	4	6.5	8.5	4	9.4	200
^t PHL	1 A	ı	3.4	6.3	8.7	3.4	9.5	ns
^t PZH	ŌĒ	V	3	5.8	8.1	3	8.9	ne
t _{PZL}	OE	ı	3.7	6.7	9.3	3.7	10.3	ns
^t PHZ	ŌĒ	V	5.4	8.1	10.3	5.4	11.3	ne
t _{PLZ}	OE	'	5	7.5	9.5	5	10.3	ns

operating characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER	TEST CO	TYP	UNIT		
C . Power dissipation	Power discipation conneitance	Outputs enabled	$C_1 = 50 pF$	f = 1 MHz	39	pF
Cpd	Power dissipation capacitance	Outputs disabled	CL = 50 pr,	1 = 1 101112	11	pr

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f = 3 \text{ ns}$, $t_f = 3 \text{ ns}$.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9202201MXA	ACTIVE	CFP	WD	48	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9202201MX A SNJ54ACT16244W D	Samples
74ACT16244DGG	ACTIVE	TSSOP	DGG	48	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM		ACT16244	Samples
74ACT16244DGGR	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16244	Samples
74ACT16244DGGRG4	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16244	Samples
74ACT16244DL	ACTIVE	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16244	Samples
74ACT16244DLG4	ACTIVE	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16244	Samples
74ACT16244DLR	ACTIVE	SSOP	DL	48	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16244	Samples
74ACT16244DLRG4	ACTIVE	SSOP	DL	48	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16244	Samples
SNJ54ACT16244WD	ACTIVE	CFP	WD	48	1	Non-RoHS & Green	SNPB	N / A for Pkg Type		5962-9202201MX A SNJ54ACT16244W D	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM

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- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





		Dimension designed to accommodate the component width
E	30	Dimension designed to accommodate the component length
K	(0	Dimension designed to accommodate the component thickness
	Ν	Overall width of the carrier tape
F	21	Pitch between successive cavity centers

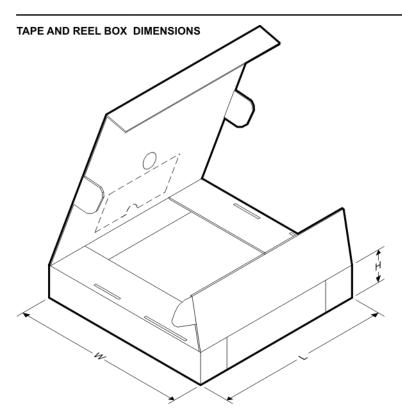
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ACT16244D0	GGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
74ACT16244E	LR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ACT16244DGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0
74ACT16244DLR	SSOP	DL	48	1000	367.0	367.0	55.0

PACKAGE MATERIALS INFORMATION

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TUBE

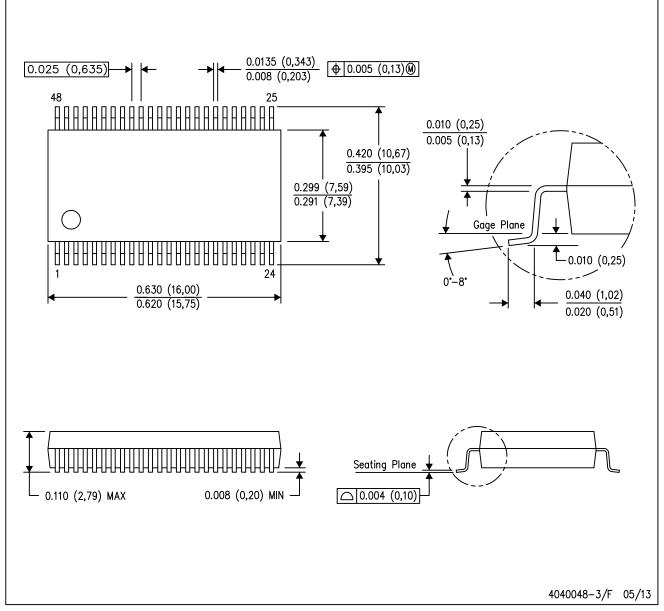


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
74ACT16244DGG	DGG	TSSOP	48	40	530	11.89	3600	4.9
74ACT16244DL	DL	SSOP	48	25	473.7	14.24	5110	7.87
74ACT16244DLG4	DL	SSOP	48	25	473.7	14.24	5110	7.87

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

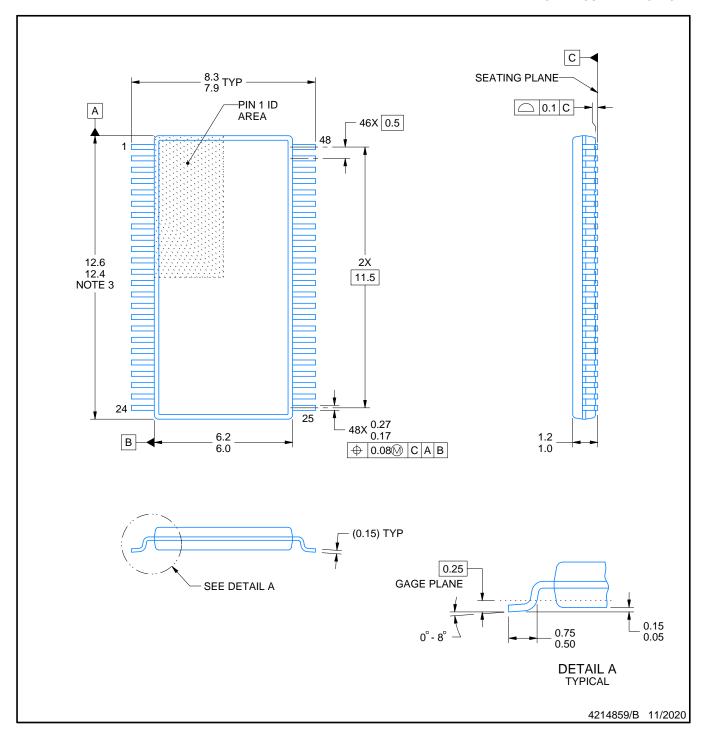
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.





SMALL OUTLINE PACKAGE



NOTES:

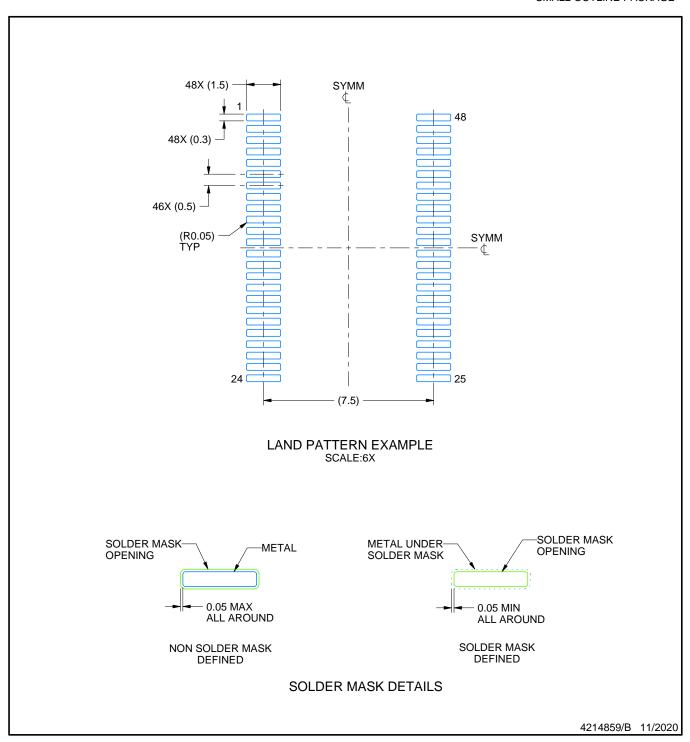
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
 4. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE

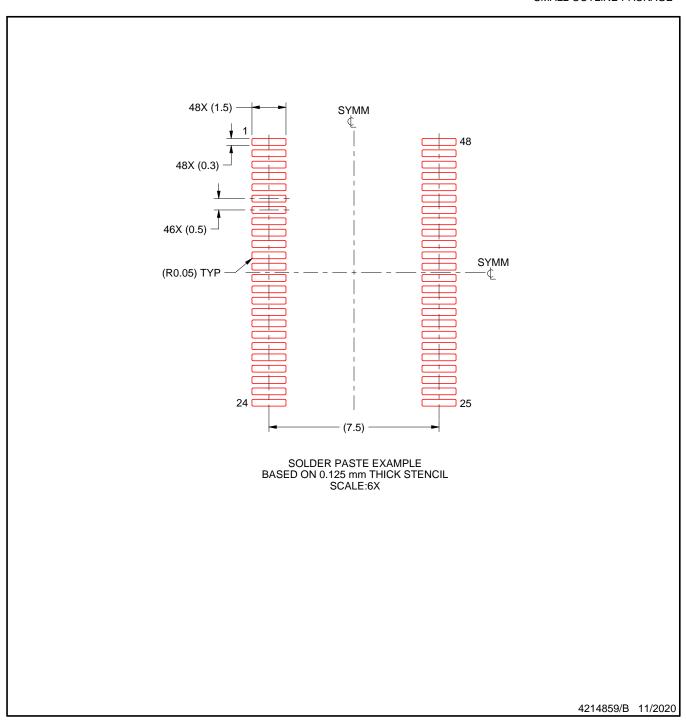


NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



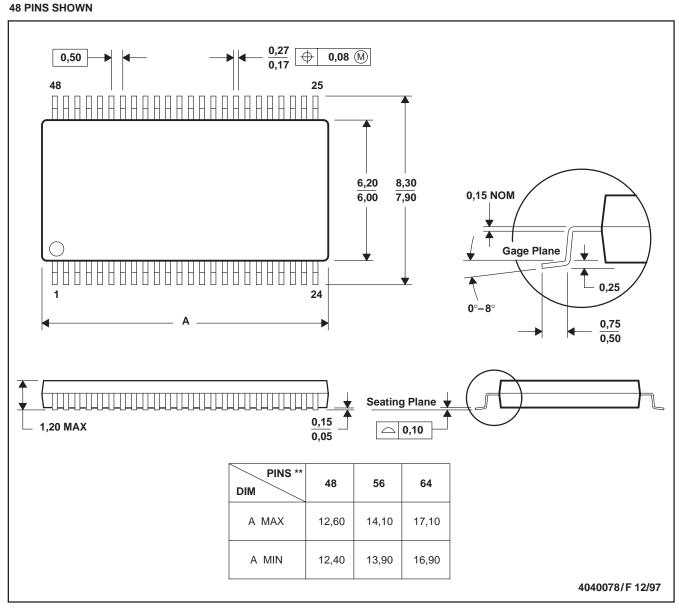
NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

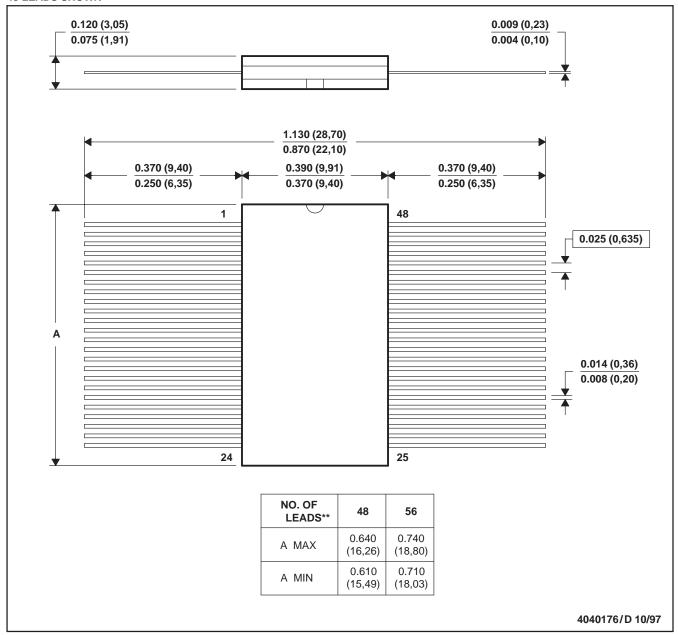
C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

WD (R-GDFP-F**)

CERAMIC DUAL FLATPACK

48 LEADS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only
- E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA

GDFP1-F56 and JEDEC MO-146AB

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LE87290YQC LE87290YQCT 74AUP1G125FW5-7 NLU2G16CMUTCG MC74LCX244MN2TWG NL17SG17P5T5G

NLV74HC125ADR2G NLVHCT245ADTR2G NLVVHC1G126DFT2G EL5623IRZ ISL15102AIRZ-T13 ISL1539IRZ-T13

MC100EP17MNG MC74HCT365ADR2G MC74LCX244ADTR2G NL27WZ126US NL37WZ16US NLU1G07MUTCG NLU2G07MUTCG NLX3G17BMX1TCG